

2SD2156, 2SD2156A

Silicon NPN triple diffusion planar type

For power amplification with high forward current transfer ratio

Features

- High forward current transfer ratio h_{FE}
- Satisfactory linearity of forward current transfer ratio h_{FE}
- Full-pack package which can be installed to the heat sink with one screw

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$)

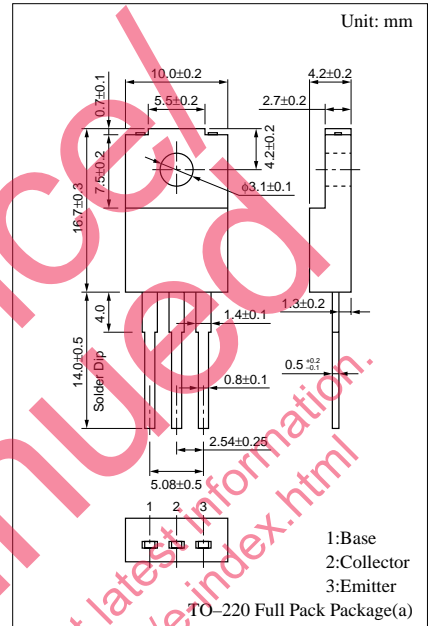
Parameter	Symbol	Rated	Unit	
Collector to base voltage	V_{CBO}	2SD2156	80	V
2SD2156A		100		
Collector to emitter voltage	V_{CEO}	2SD2156	60	V
2SD2156A		80		
Emitter to base voltage	V_{EBO}	6	V	
Peak collector current	I_{CP}	6	A	
Collector current	I_C	3	A	
Base current	I_B	1	A	
Collector power dissipation	P_C	$T_C=25^\circ\text{C}$	25	W
$T_a=25^\circ\text{C}$		2		
Junction temperature	T_j	150	$^\circ\text{C}$	
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$	

Electrical Characteristics ($T_C=25^\circ\text{C}$)

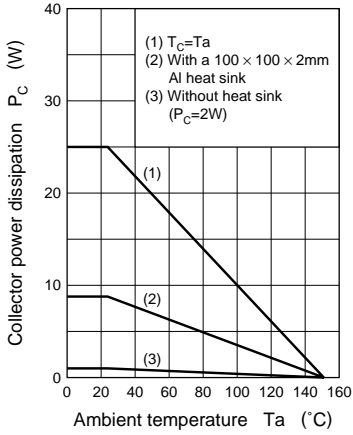
Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I_{CBO}	$V_{CB} = 80\text{V}, I_E = 0$			100	μA
2SD2156A		$V_{CB} = 100\text{V}, I_E = 0$			100	
Collector cutoff current	I_{CEO}	$V_{CE} = 40\text{V}, I_B = 0$			100	μA
Emitter cutoff current	I_{EBO}	$V_{EB} = 6\text{V}, I_C = 0$			100	μA
Collector to emitter voltage	V_{CEO}	$I_C = 25\text{mA}, I_B = 0$	2SD2156	60		V
2SD2156A			80			
Forward current transfer ratio	h_{FE}^*	$V_{CE} = 4\text{V}, I_C = 0.5\text{A}$	500		2500	
Collector to emitter saturation voltage	$V_{CE(sat)}$	$I_C = 2\text{A}, I_B = 0.05\text{A}$			1	V
Transition frequency	f_T	$V_{CE} = 12\text{V}, I_C = 0.2\text{A}, f = 10\text{MHz}$		50		MHz

* h_{FE} Rank classification

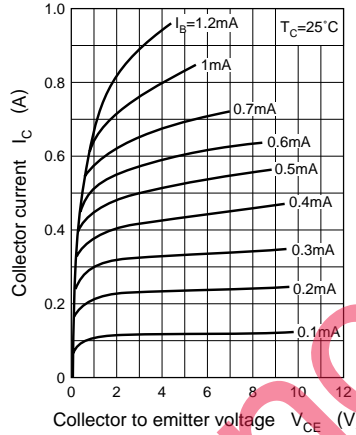
Rank	Q	P	O
h_{FE}	500 to 1000	800 to 1500	1200 to 2500



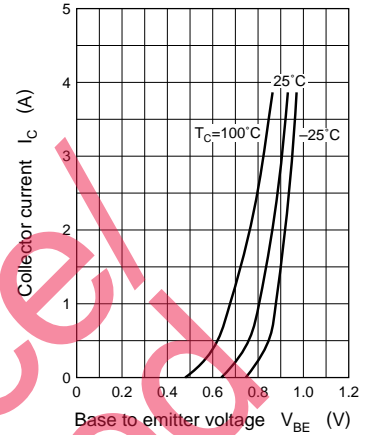
$P_C - T_a$



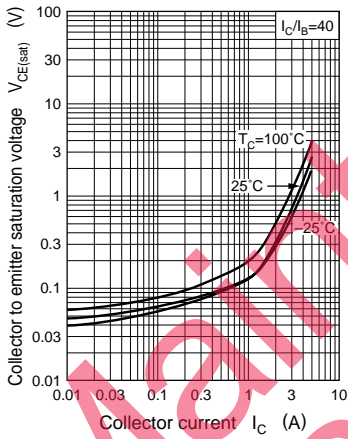
$I_C - V_{CE}$



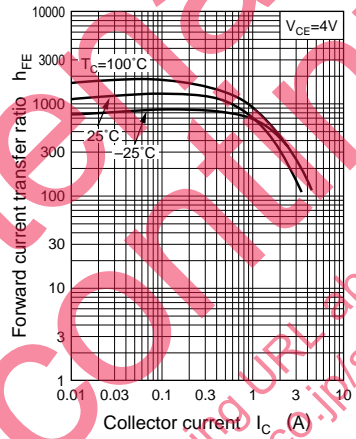
$I_C - V_{BE}$



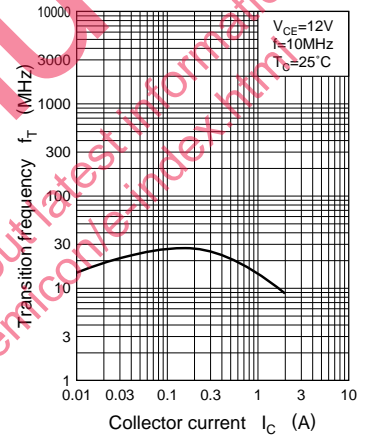
$V_{CE(sat)} - I_C$



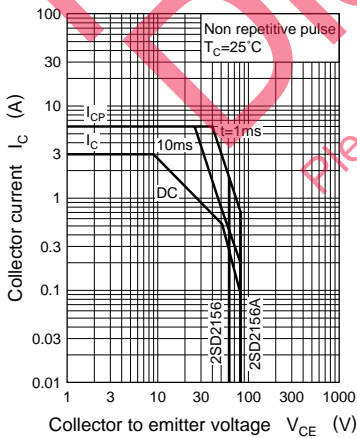
$h_{FE} - I_C$



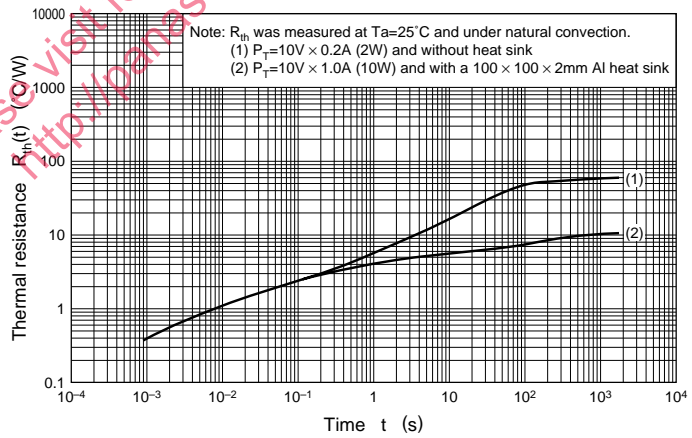
$f_T - I_C$



Area of safe operation (ASO)



$R_{th(t)} - t$



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